



Title of Change:	Remove 100% X-Ray for tape and reel units for SOT23 1.3mil cu wire device S2ZMMBZ27XALT1G/T3G	
Effective date:	01 Sep 2021	
Contact information:	Contact your local ON Semiconductor Sales Office or Jim.Peng@onsemi.com	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change Category:	Assembly Change	
Change Sub-Category(s):	Manufacturing Process Change	
Sites Affected:		
ON Semiconductor Sites		External Foundry/Subcon Sites
Leshan Phoenix Semiconductor, China		None
Description and Purpose:		
<p>This product bulletin announces to remove 100% X-Ray that being performed after FT to improve assembly cycle time. Monitor data of >13 M devices inspected after 1.3 mils wire implemented shows no any disturbed wire. 100% X-Ray for short and leakage reject units will be performed.</p> <p>The change will not impact form, fit, or function of product(s).</p> <p>Please refer to below table for the detail change</p>		
	Before Change	After Change
X-Ray Control	100% X-Ray for short and leakage reject units 100% X-Ray for tape and reel units	100% X-Ray for short and leakage reject units
List of Affected Standard Parts:		
Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u> .		
S2ZMMBZ27XALT1G	S2ZMMBZ27XALT3G	